

# Exhibit B



02 FEB 16 1998 1:41:16 PM 1 HELLER, IND

KB ELECTRONICS INC

NO.156

P.2/2

001

Sheet 1

Environment	Rate	Air	Nitrogen	Ultrasonic
X Dimension	0.159	0.27	0.225	0.24
Y Dimension	0.159	0.229	0.238	0.288
Thickness PCB	0	0.0609	0.0612	0.0608
Thickness Reflowed	0.088	0.07	0.067	0.067
Finished Thickness	0.088	0.091	0.0958	0.0882
Area	0.01906	0.0377	0.05355	0.06912
Volume	0	0.992	1.637	2.481
% Area Increase	0			
Process				
Dip Volume tab of Solder into Multicore NC-73 rework flux				
Deposit tab, flux side down onto bare copper coupon coated with Entek CJ-106A				
Reflow under air for 120 seconds				
Reflow under air with Ultrasonics for 90 seconds				
Reflow in Nitrogen in 10 zone reflow furnace				
Ultrasonic: Rubber band onto Ultrasonic horn and heat using a Chipsonator with ~1/4" clearance from nozzle				

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